PCB ASSEMBLY CAPABILITIES

pcbwhiz
GLOBAL PROTOTYPING

Category	Description	Technical performance
Data	Manufacturing data	Working Gerber, BOM, Pick and place (PnP), Assembly plan
SMT	PCB Board Thickness	0.1mm (min), 8mm (max)
	PCB Panel Size	50mmx50mm (min), 810mmx710mm (max)
	SMT Component Size Range	01005 (min), 55mmx100mmx28mm (max)
	SMT Component Pitch Range	≥0.35mm
	SMT Repeat Accuracy	±0.025mm
	Protective N2 Gas Purity Of SMT	99.999%
	Production Capacity Points	141000/h
	Equipment	Automatic Loading Machine Solder Paste Printer 3D SPI (Solder Paste Inspection) 2D AOI, 3D AOI 10-Zone Reflow Oven Automatic Magazine Unloader
Equipment Parameters	Solder Paste Printer	Accuracy: X, Y: ±25μm; θ: ±2° Cycle Time: ≤7.5s Printable Substrate Range: 50×50mm to 510×510mm
	SPI (Solder Paste Inspection)	Accuracy: X, Y: ±10μm; θ: ±2° Cycle Time: ≤7.5s Inspection Substrate Range: 50×50mm to 510×510mm
	Nitrogen Reflow Oven	Max width: 460mm Temperature Deviation: +/-1°C Reflow Temperature Range: Room Temp. --- 300℃ Protecting Air: N2
	3D AOI	Resolution: 12μm, equipped with 1200 pixels Inspection Size: 50×50mm to 510×510mm Moiré Stripe 3D Imaging Efficient Detection of Soldering Defects
DIP	The Max Width of PCBA	350mm (Selective soldering) 500mmx450mm (Wave soldering)
	DIP Component Size Range	Height of component <120mm
	Protective N2 Gas Purity Of DIP	99.999%
	Equipment	2D AOI Automatic Wave Soldering Machine
Quality	FAI inspection	Yes
	X-ray Inspection	Yes
	Flying Probe Testing	Yes
	Environmental Stress Screening (ESS)	Yes
	Electromagnetic Compatibility (EMC) Testing	Yes
	Automated Optical Inspection (2D/3D AOI)	Yes
	In-Circuit Testing (ICT)	Yes
	Functional Testing (FCT	Yes
	Burn-In Testing	Yes
	Boundary Scan Testing	Yes
Hybrid Rework System	PCBA Board size	50mmx50mm~ 390mmx300mm
	Component size	Chip 01005*up to 60x60mm
	Placement accuracy	±0.025 μm
	Working distance	30-60 mm to top heater 35 mm to bottom heater
Standards and certificates	IPC	IPC-A-610 (latest version) Class 2, 3
	ISO	IATF16949, ISO9001, ISO14000, ISO27001